Alliance Memory Inc.
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Product Discontinue Notification (PDN)

Date: 21 November 2025 **PDN TRACKING NO: PDN#21112025**

Subject: Product Discontinue Notification (PDN) for Alliance Memory **16GB eMMC v5.1** Rev.0 Part Numbers **ASFC16G31M-51BIN/TR** offered in 153ball FBGA package in Industrial Temperature Grade.

Affected Part Numbers	ASFC16G31M-51BIN & ASFC16G31M-51BINTR
Description of Change:	End-Of-Line of ASFC16G31M-51BIN / TR parts. Products will be offered in revision A
Reason for Change	MLC NAND Wafer FAB Line shutdown Products will be offered in revision A for better longevity
Traceability, Guidelines	Traceable through marketing orderable part numbers
Alternative Part	Refer to Table.1
Summary of Alternative	Alternative parts uses active TLC NAND Flash in -25C to 85C extended Commercial Temp Grade.

***Table. 1:* Affected and Alternative Active Part Numbers**

Product	Alliance EOL Part Numbers	Alliance Alternative Part Number
16GB eMMC-v5.1 (Managed NAND Flash)	ASFC16G31M-51BIN ASFC16G31M-51BINTR	ASFC16G31T**A**-51BCN ASFC16G31T**A**-51BCNTR

Last Time Buy Date:	May 21st , 2026
Last Time Ship Date:	November 21st, 2026
Sample Availability Date for alternative part number	December 1st 2025
PDN Effective Date	November 21 , 2025

Please contact your local sales representative if you have any questions regarding this PDN.

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Dear Valued Customer:

This letter provides End–of–Life (EOL) notice of products for Alliance Memory **16GB eMMC v5.1** Rev.0 Industrial Temperature Grade part numbers **ASFC16G31M-51BIN/TR**. Alternatives to these products will continue to be offered as rev.A option in Extended Commercial Temperature Grade. Refer annexure for comparison

The delivery deadline is **November 21st, 2026** with last time buy (LTB) deadline on **May 21st, 2026**. Please note that the standard shipment dates will apply in general and extended delivery dates must be pre-arranged and accepted in writing by Alliance Memory Management.

Alliance Memory Inc. will make all reasonable commercial efforts to honor all purchase orders placed before LTB and scheduled delivery dates but reserves the right to not accept new orders or to cancel existing orders if they cannot be fulfilled.

Samples for Alternative part numbers are as listed in Table.1 are available for customers to order samples from December 01st 2025 to start verification or qualification procedures.

Please contact your local Alliance Memory representative if you have any questions regarding this PDN notification

Yours faithfully

David Bagby

President
Alliance Memory Inc.

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ASFC16G31M-51BIN vs ASFC16G31TA-51BCN Comparison

Parameter \ Part Number & result	ASFC16G31M-51BIN	ASFC16G31TA-51BCN	Comparison remark
Product Description	**eMMC v5.1 , Rev.0**	**eMMC v5.1, rev.A**	
Capacity	16GB	16GB	Same
Bus Width	x1 (default), x4 & x8	x1 (default) , x4 & x8	Same
eMMC Version	v5.1 (backward compatible with previous MMC versions)	v5.1 (backward compatible with previous MMC versions)	Same
Operating Power Supply (Controller)	VccQ = 1.70V ~ 1.95V or 2.7V ~ 3.6V	VccQ = 1.70V ~ 1.95V or 2.7V ~ 3.6V	Same
Operating Power Supply (NAND)	Vcc = 2.7V~3.6V	Vcc = 2.7V~3.6V	Same
Operating Temperature	Industrial (Ta = -40°C ~ 85°C)	Extended Commercial (Ta = -25°C ~ 85°C)	Different
Storage Temperature	-40°C ~ 85°C	-40°C ~ 85°C	Same
Clock Frequency	MMC I/F Clock: 0~200MHz (Max) MMC I/F Boot Freq: 0~52MHz	MMC I/F Clock: 0~200MHz (Max) MMC I/F Boot Freq: 0~52MHz	Same
Interface Timing Mode	HS200/ HS400	HS200/ HS400	Same
NAND Flash Component	Density: 128Gb Die:1, MLC	Density: 128Gb Die:1, TLC	Different
Enhance mode support Configure pSLC mode	No	Yes	Rev.A better
Boot Partition 1	4096KB	4096KB	Same
Boot Partition 2	4096KB	4096KB	Same
Sequential Performance (HS400)	Write: 80MB/s Read = 140MB/s	Write: 195MB/s Read =315MB/s	Comparable
Active Power Consumption	VCCQ = 120mA VCC = 120mA	VCCQ = 160mA VCC = 90mA	Comparable
Standby Power Consumption	VCCQ = 600uA VCC = 50uA	VCCQ = 100uA VCC = 50uA	Comparable
Package Type	153-ball TFBGA	153-ball TFBGA	Same
Package Outer Dimensions	11.5 x 13 x 1.0mm	11.5 x 13 x 1.0mm	Same
Package Ball pitch/matrix	0.5mm pitch, 6.5mm x 6.5mm	0.5mm pitch, 6.5mm x 6.5mm	Same
Package Material	Pb and Halogen Free	Pb and Halogen Free	Same
Pin to Pin Compatible	Yes.		